

ABSTRACT

In a shielding configuration of a chip part, a shielding effect and a cooling effect are sufficiently obtained at the same time. In an electronic device including a chip part to be disclosed, a shielding conductor 3 includes a ceiling plate section 4 covering the chip part 1 and side plate sections 5 which are formed to be united with the ceiling plate section 4 and to be at a position lower than the ceiling plate section 4 and which are arranged on both sides in a horizontal direction of the chip part 1, and openings 8 are formed in both side ends in a front-rear direction of the shielding conductor 3 to open both sides in a front-rear direction of the chip part 1, and the side plate sections 5 of the shielding conductor 3 are electrically connected via a plurality of shielding bumps 17 in the front-rear direction to a ground layer pattern 11 of a mounting substrate 10.